



U.S. Ser. No. 10/017,490
File No. 6308

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Pennace et al.

GROUP: 2831

SERIAL NO: 10/017,490

EXAMINER: Chau N. Nguyen

FILED: 12/14/2001

FOR: CONDUCTIVE COMPOSITE FORMED OF A THERMOSET MATERIAL

**Box Non-Fee Amendment
Assistant Commissioner of Patents
Washington, D.C. 20231**

Sir:

AMENDMENT

In response to the Office Action mailed on December 26, 2002, please amend the above-identified application as follows:

THE DRAWINGS:

Enclosed herewith is a new set of drawings (two pages) comprising Figures 1-8. These include added reference numerals in Figures 1 and 2, and a showing of the optional second adhesive in Figure 2. Subject to the examiner's approval, these new drawings should be substituted for those now on file in this application.

IN THE SPECIFICATION:

Please amend the specification as follows:

Change the paragraph at line 15 of page ⁴ 2 to read as follows:

--Figure 2 is an exploded view of the composite shown in Figure 1, with the addition of an optional second adhesive for securing the conductive layer to the upper surface of the first film.--

#11/B w/attach
D. Evans
2.28.03